

# FAST CMOS BUFFER/CLOCK DRIVER

# IDT74FCT810BT/CT

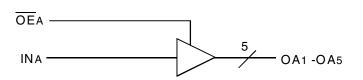
### **FEATURES:**

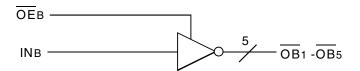
- 0.5 MICRON CMOS Technology
- Guaranteed low skew < 600ps (max.)</li>
- Very low duty cycle distortion < 700ps (max.)</li>
- · Low CMOS levels
- · TTL compatible inputs and outputs
- · TTL level output voltage swings
- High drive: -32mA loh, +48mA lol
- · Two independent output banks with 3-state control:
  - One 1:5 inverting bank
  - One 1:5 non-inverting bank
- · Available in QSOP, SSOP, and SOIC packages

### **DESCRIPTION:**

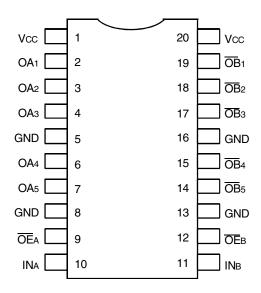
The 74FCT810T is a dual bank inverting/ non-inverting clock driver built using advanced dual metal CMOS technology. It consists of two banks of drivers, one inverting and one non-inverting. Each bank drives five output buffers from a standard TTL-compatible input. The FCT810T has low output skew, pulse skew and package skew. Inputs are designed with hysteresis circuitry for improved noise immunity. The outputs are designed with TTL output levels and controlled edge rates to reduce signal noise. The part has multiple grounds, minimizing the effects of ground inductance.

## FUNCTIONAL BLOCK DIAGRAM





### **PIN CONFIGURATION**



QSOP/ SOIC/ SSOP TOP VIEW

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# ABSOLUTE MAXIMUM RATINGS(1)

Symbol	Description	Max	Unit
VTERM	Terminal Voltage with Respect to GND	-0.5 to +7	V
Tstg	Storage Temperature	-65 to +150	°C
lout	DC Output Current	-60 to +120	mA

#### NOTE:

Stresses greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause
permanent damage to the device. This is a stress rating only and functional operation
of the device at these or any other conditions above those indicated in the operational
sections of this specification is not implied. Exposure to absolute maximum rating
conditions for extended periods may affect reliability.

# **CAPACITANCE** (TA = $+25^{\circ}$ C, f = 1.0MHz)

Symbol	Parameter <sup>(1)</sup>	Conditions	Тур.	Max.	Unit
CIN	Input Capacitance	VIN = 0V	4.5	6	pF
Соит	Output Capacitance	Vout = 0V	5.5	8	pF

#### NOTE:

1. This parameter is measured at characterization but not tested.

## **PIN DESCRIPTION**

Pin Names	Description
OEA, OEB	3-State Output-Enable Inputs (Active LOW)
INA, INB	Clock Inputs
ОАх, ОВХ	Clock Outputs

## DC ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE

Following Conditions Apply Unless Otherwise Specified: Commercial:  $Ta = 0^{\circ}C$  to  $+70^{\circ}C$ ,  $Vcc = 5V \pm 5\%$ 

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Unit
VIH	Input HIGH Level (Input pins)	Guaranteed Logic HIGH	Guaranteed Logic HIGH Level		_	_	V
VIL	Input LOW Level	Guaranteed Logic LOW	Level	<u> </u>	_	0.8	V
lін	Input HIGH Current (Input pins)	Vcc = Max.	VI = 2.7V	_	_	±1	μΑ
liL	Input LOW Current (Input pins)	Vcc = Max.	VI = 0.5V	<u> </u>	_	±1	μΑ
lozh	High Impedance Output Current	Vcc = Max.	Vo = 2.7V	_	_	±1	μΑ
lozL	(3-State Output pins)		Vo = 0.5V	T -	_	±1	
lı	Input HIGH Current	Vcc = Max., VI = Vcc (Max.)		_	_	±1	μΑ
Vik	Clamp Diode Voltage	VCC = Min., IIN = -18mA		_	-0.7	-1.2	V
los	Short Circuit Current	Vcc = Max., Vo = GNE	Vcc = Max., Vo = GND <sup>(3)</sup>		-120	-225	mA
Vон	Output HIGH Voltage	Vcc = Min.	Iон = -15mA	2.4	3.3	_	V
		VIN = VIH or VIL	$IOH = -32mA^{(4)}$	2	3	_	
Vol	Output LOW Voltage	Vcc = Min.	IoL = 48mA	<u> </u>	0.3	0.55	V
		VIN = VIH or VIL					
loff	Input/Output Power Off Leakage	Vcc = 0V, Vin or Vo≤	Vcc = 0V, Vin or Vo ≤4.5V		_	±1	μΑ
Vн	Input Hysteresis for all inputs	_		_	150	_	mV
ICCL ICCH ICCZ	Quiescent Power Supply Current	Vcc = Max., Vin = GNE	or Vcc	_	5	500	μА

#### NOTES

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5V, +25°C ambient.
- 3. Not more than one output should be shorted at one time. Duration of the test should not exceed one second.
- 4. Duration of the condition should not exceed one second.

# **POWER SUPPLY CHARACTERISTICS**

Symbol	Parameter	Test Conditions <sup>(1)</sup>		Min.	Typ. <sup>(2)</sup>	Max.	Unit
Δlcc	Quiescent Power Supply Current	Vcc = Max.		_	0.5	2	mA
	TTL Inputs HIGH	$VIN = 3.4V^{(3)}$	_				
ICCD	Dynamic Power Supply Current <sup>(4)</sup>	Vcc = Max.	VIN = VCC	_	60	100	μA/MHz
		Outputs Open	VIN = GND				
		OEA = OEB = GND					
		50% Duty Cycle					
Ic	Total Power Supply Current <sup>(6)</sup>	Vcc = Max.	VIN = VCC	_	7.5	13	mA
		Outputs Open	Vin = GND				
		fo = 25MHz					
		50% Duty Cycle	VIN = 3.4V	_	7.8	14	
		OEA = GND, OEB = VCC	VIN = GND				
		Vcc = Max.	VIN = VCC	_	30	50.5 <sup>(5)</sup>	
		Outputs Open	VIN = GND				
		fo = 50MHz					
		50% Duty Cycle	VIN = 3.4V	_	30.5	52.5 <sup>(5)</sup>	
		OEA = OEB = GND	VIN = GND				

#### NOTES:

- 1. For conditions shown as Max. or Min., use appropriate value specified under Electrical Characteristics for the applicable device type.
- 2. Typical values are at Vcc = 5V, +25°C ambient.
- 3. Per TTL driven input (VIN = 3.4V); all other inputs at Vcc or GND.
- 4. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
- 5. Values for these conditions are examples of the Ic formula. These limits are guaranteed but not tested.
- 6. IC = IQUIESCENT + INPUTS + IDYNAMIC
  - $IC = ICC + \Delta ICC DHNT + ICCD (foNo)$
  - Icc = Quiescent Current (IccL, IccH and Iccz)
  - $\Delta Icc$  = Power Supply Current for a TTL High Input (VIN = 3.4V)
  - DH = Duty Cycle for TTL Inputs High
  - NT = Number of TTL Inputs at DH
  - ICCD = Dynamic Current Caused by an Input Transition Pair (HLH or LHL)
  - fo = Output Frequency
  - No = Number of Outputs at fo
  - All currents are in milliamps and all frequencies are in megahertz.

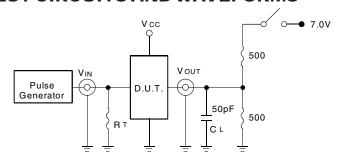
# **SWITCHING CHARACTERISTICS OVER OPERATING RANGE**(3,4)

			FCT810BT		FCT810CT		
Symbol	Parameter	Conditions <sup>(1)</sup>	Min. <sup>(2)</sup>	Max.	Min. <sup>(2)</sup>	Max.	Unit
tPLH	Propagation Delay	CL = 50pF	1.5	4.5	1.5	4.3	ns
tphl	INA to OAx, INA to OBX	$RL = 500\Omega$					
₽	Output Rise Time		_	1.5	_	1.5	ns
tF	Output Fall Time		_	1.5	_	1.5	ns
tsk1(0)	Output skew (same bank): skew between outputs of		_	0.5	_	0.3	ns
	same bank and same package (same transition)						
tsk2(0)	Output skew (all banks): skew between outputs of		_	0.7	_	0.6	ns
	all banks of same package (inputs tied together)						
tsk(p)	Pulse skew: skew between opposite transitions		_	0.7	_	0.7	ns
	of same output ( tphl tplh )						
tsk(T)	Package skew: skew between outputs of different		_	1.2	_	1	ns
	packages at same power supply voltage,						
	temperature, package type and speed grade						
tPZL	Output Enable Time		1.5	6	1.5	5	ns
tpzh	OEA to OAx, OEB to OBX						
tPLZ	Output Disable Time		1.5	6	1.5	5	ns
tphz	OEA to OAx, OEB to OBX						

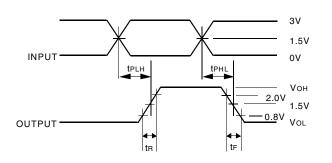
#### NOTES:

- 1. See test circuits and waveforms.
- 2. Minimum limits are guaranteed but not tested on Propagation Delays.
- 3. tplh, tphl, tsk(t) are production tested. All other parameters guaranteed but not production tested.
  4. Propagation delay range indicated by Min. and Max. limit is due to Vcc, operating temperature and process parameters. These propagation delay limits do not imply skew.

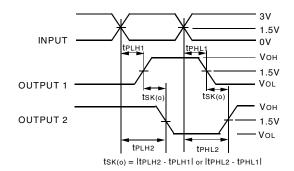
# **TEST CIRCUITS AND WAVEFORMS**



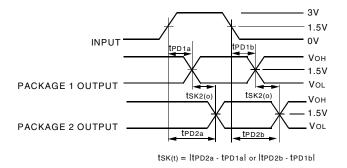
Test Circuit for All Outputs



Package Delay



Output Skew (All Banks) - tSK2(0)



Package Skew - tsk(T)

#### NOTES:

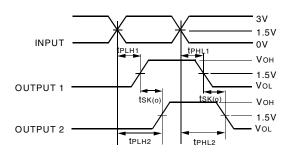
- 1. Diagram shown for input Control Enable-LOW and input Control Disable-HIGH
- 2. Pulse Generator for All Pulses: Rate ≤1.0MHz; tF ≤2.5ns; tR ≤2.5ns

# **SWITCH POSITION**

Test	Switch
Disable LOW Enable LOW	Closed
Disable HIGH Enable HIGH	GND

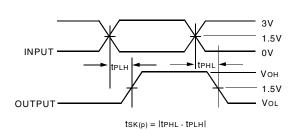
#### **DEFINITIONS:**

- CL = Load capacitance: includes jig and probe capacitance.
- RT = Termination resistance: should be equal to ZouT of the Pulse Generator.

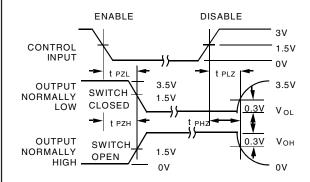


tsk(o) = |tplh2 - tplh1| or |tphl2 - tphl1|

Output Skew (Same Bank) - tsk1(0)



Pulse Skew - tsk(P)

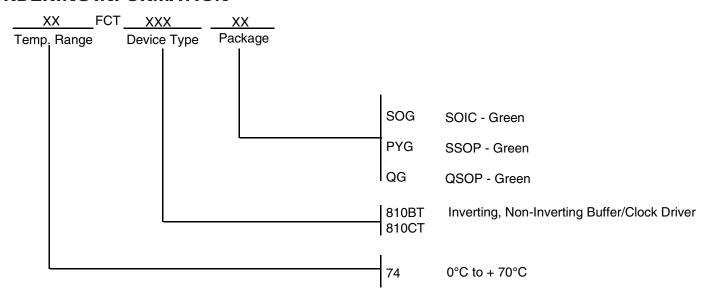


Enable and Disable Times

#### NOTE:

1. Package 1 and Package 2 are same device type and speed grade.

# **ORDERING INFORMATION**



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